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Attorney Docket No. 10112581

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yi-Nan CHEN, Hsin-Chuan TSAI

Filed: 7/28/2003

Appl. No.: 10/628,894

Examiner: PHAM, THANH V

Conf. No.: 7425

Art Unit: 2823

Title: METHOD FOR FORMING BOTTLE-SHAPED TRENCH

Date: November 4, 2004

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION COVER SHEET

Sir:

Attached hereto please find an Request for Reconsideration filed in response to the Office Action mailed on **August 12, 2004**.

No fee is believed to be due in connection with this Amendment. If, however, the Commissioner considers that a fee is due in connection with this Amendment, authorization is made to charge any fee which may be required to Deposit Account No. **502447**.

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Nelson A. Quintero

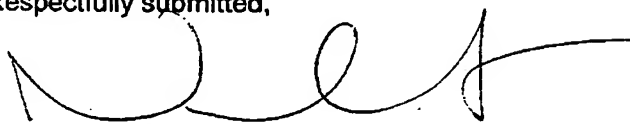
(Name of Person Transmitting)

(Signature)

November 4, 2004

(Date)

Respectfully submitted,

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P107756NAQ

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REQUEST FOR RECONSIDERATION

Sir:

In response to the Office Action mailed on **August 12, 2004**, Applicant respectfully requests that the above-identified application be reconsidered in view of the remarks which follow, that each of the pending claims be allowed, and that the application be passed to issue.

REMARKS

Claims 1-20 are pending. Claims 1-20 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Forster et al (US 6,455,369) in combination with Wolf et al (Silicon Processing for the VLSI, Vol. 1). Applicant respectfully traverses the rejections for at least the reasons as follow.

Forster et al disclose a method for fabricating a trench capacitor, in which a lower trench region is enlarged for the purpose of enlarging the surface of the electrodes by means of an etching operation. Please see col. 12 lines 19-21, col. 13, lines 55-58, and FIGS. 3I and 5I of Forster et al. Namely, in Forester et al, the lower trench region is widened by means of a further etching step.

Wolf et al disclose wet etching silicon dioxide with hydrofluoric (HF) acid. Please see page 532 of Wolf et al. Wolf et al teach the density of thermally grown fused silica is less than that of

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